

8935

High productivity patterned wafer inspection system detects a wide variety of critical defects that affect the yield and reliability of semiconductor chips

BENEFITS:

The 8935 provides high throughput, inline defect detection and binning, helping automotive chipmakers:

- Accurately identify and quickly resolve production process issues that can affect final chip quality
- Implement Zero Defect screening strategies by monitoring 100% of die on all wafers at critical process steps to remove die that may fail from the supply chain at the source, where cost is lowest
- Produce new devices and move to smaller design nodes by providing an extendible, cost-effective platform that provides the inspection sensitivity and AI technology needed to isolate critical defects and the throughput to support monitoring and screening applications

TECHNOLOGIES:

- Multi-mode LED scanning capability with high NA optics
- High resolution operating mode
- DefectWise® AI-based defect discovery and binning technology
- DesignWise™ and FlexPoint™ precise area inspection technologies
- Advanced noise suppression algorithms
- I-PAT® inline screening solution

APPLICATIONS:

- Inline process monitoring with high lot and wafer sampling for reduced excursion risk
- Process tool monitoring
- Outgoing quality control of final patterned wafers
- Fully automated die-level screening solution with I-PAT



MARKETS:

Chip manufacturing

larger design node devices for automotive, IoT, 5G, consumer electronics, industrial (military, aerospace, medical)

PLATFORM:

- Customizable configurations
- Extendible
- Upgradeable

WAFER SIZES:

- 300mm
- 200mm
- 150mm

MORE INFORMATION: www.kla.com/products/chip-manufacturing/defect-inspection-review#product-8-series